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AONR36368-MS

Product specification

Description

The AONR36368-MS uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V.

This device is suitable for use as a Battery protection or in other Switching application.

Features

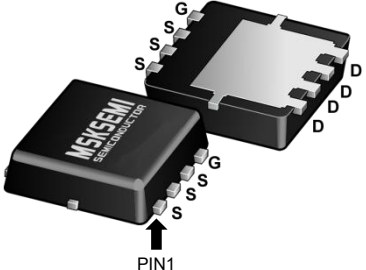
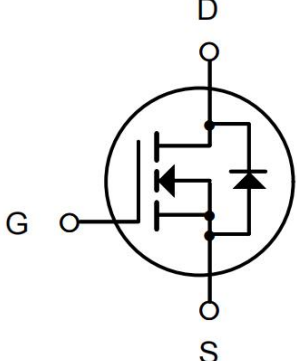
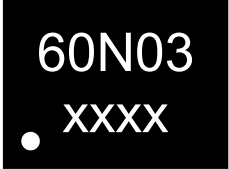
$V_{DS} = 30V$ $I_D = 60A$

$R_{DS(ON)} < 8m\Omega$ @ $V_{GS} = -10V$

Application

- Battery protection
- Load switch
- Uninterruptible power supply

Reference News

PACKAGE OUTLINE	N-Channel MOSFET	Marking
		
<p>DFN3X3-8L</p>		

Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	60	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	20	A
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	15	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	12	A
I _{DM}	Pulsed Drain Current ²	140	A
EAS	Single Pulse Avalanche Energy ³	115.2	mJ
I _{AS}	Avalanche Current	48	A
P _D @T _C =25°C	Total Power Dissipation ⁴	59	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C
R _{θJA}	Thermal Resistance Junction-ambient ¹	62	°C/ W
R _{θJC}	Thermal Resistance Junction-Case ¹	2.1	°C/ W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain- Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30	---	---	V
ΔBV _{DSS} /ΔT _J	BVDSS Temperature Coefficient	Reference to 25 °C , I _D =1mA	---	0.027	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =20A	---	6	8	mΩ
		V _{GS} =4.5V , I _D =10A		7.5	10	
V _{GS(th)}	Gate Threshold Voltage		1.2	---	2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =250uA	---	-5.8	---	Mv/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J = 25 °C	---	---	1	uA
		V _{DS} =24V , V _{GS} =0V , T _J = 55 °C	---	---	5	
I _{GSS}	Gate- Source Leakage Current	V _{GS} = ±20V , V _{DS} =0V	---	---	± 100	nA
g _{fs}	Forward Transconductance	V _{DS} =5V , I _D =30A	---	43	---	S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz	---	1.7	---	Ω
Q _g	Total Gate Charge (4.5V)		---	20	---	nC
Q _{gs}	Gate- Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =15A	---	7.6	---	
Q _{gd}	Gate- Drain Charge		---	7.2	---	
T _{d(on)}	Turn- On Delay Time		---	7.8	---	ns
T _r	Rise Time	V _{DD} =15V , V _{GS} =10V , R _G =3.3 Ω	---	15	---	
T _{d(off)}	Turn- Off Delay Time		---	37.3	---	
T _f	Fall Time	I _D =15A	---	10.6	---	
C _{iss}	Input Capacitance		---	2295	---	pF
C _{oss}	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz	---	267	---	
C _{rss}	Reverse Transfer Capacitance		---	210	---	
I _s	Continuous Source Current ^{1, 6}	V _G =V _D =0V , Force Current	---	---	40	A
I _{SM}	Pulsed Source Current ^{2, 6}		---	---	140	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _s =1A , T _J = 25 °C	---	---	1	V

Diode Characteristics

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3 .The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=34A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

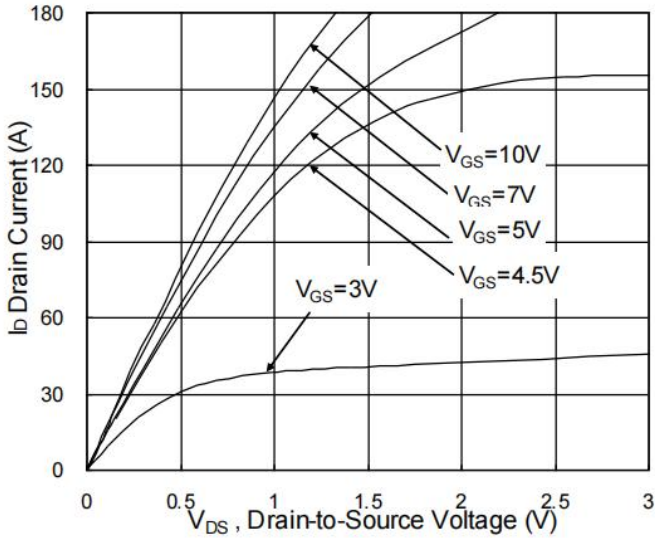


Fig.1 Typical Output Characteristics

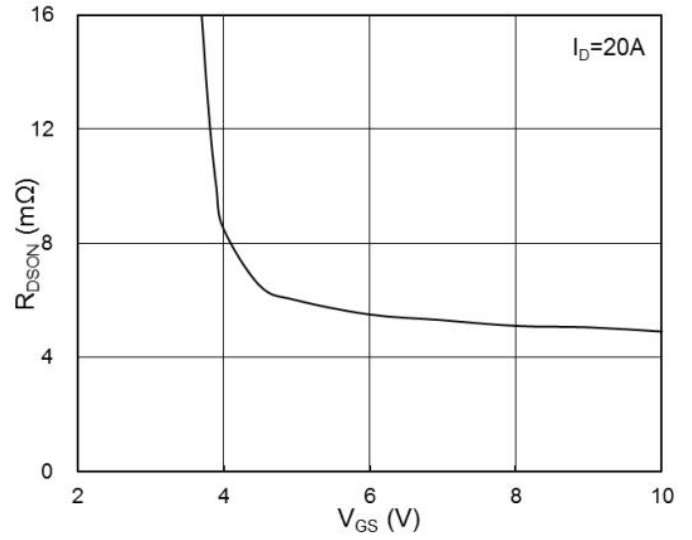


Fig.2 On-Resistance vs. G-S Voltage

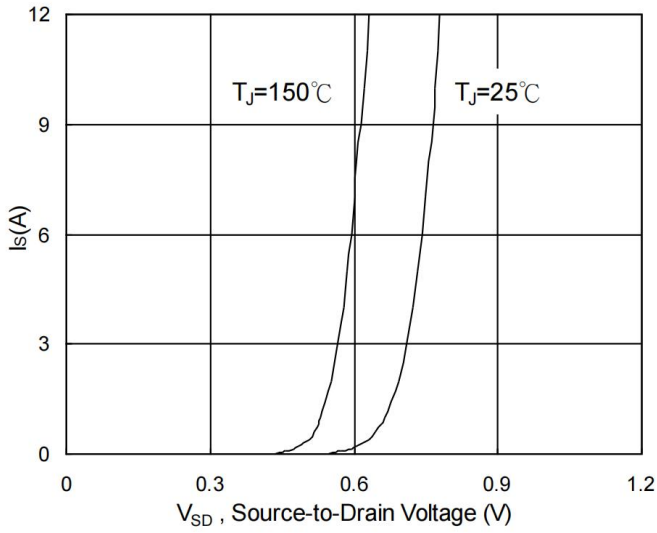


Fig.3 Forward Characteristics of Reverse

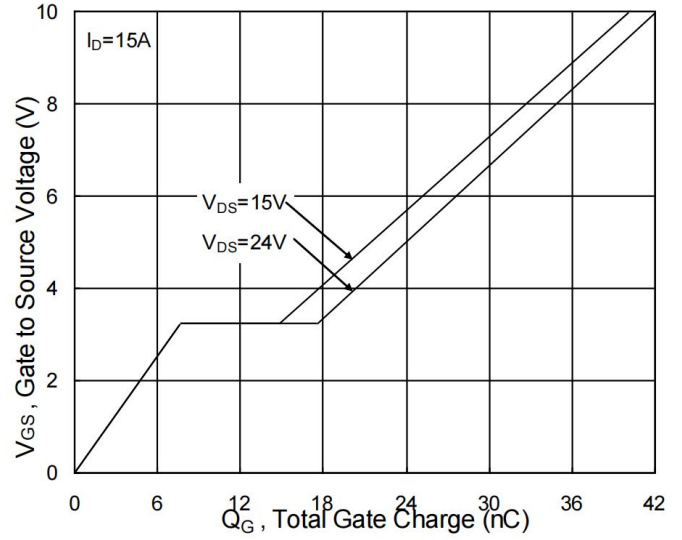


Fig.4 Gate-Charge Characteristics

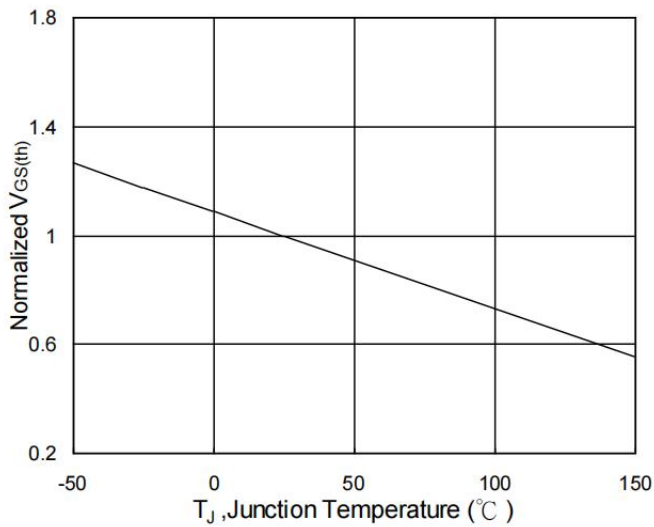


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

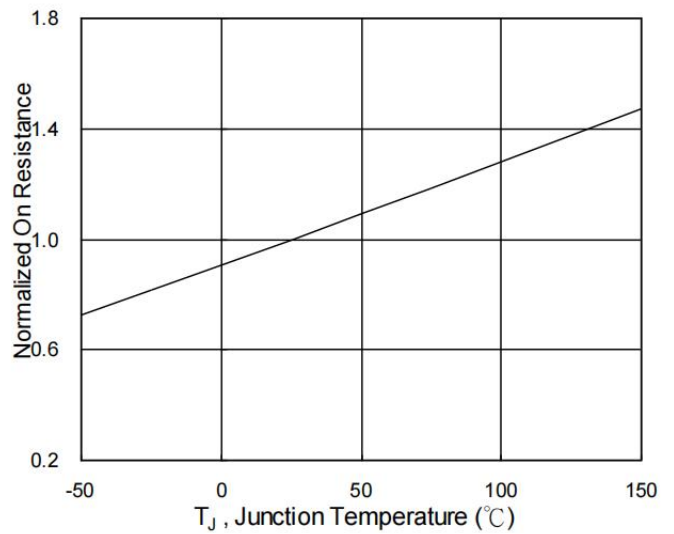


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

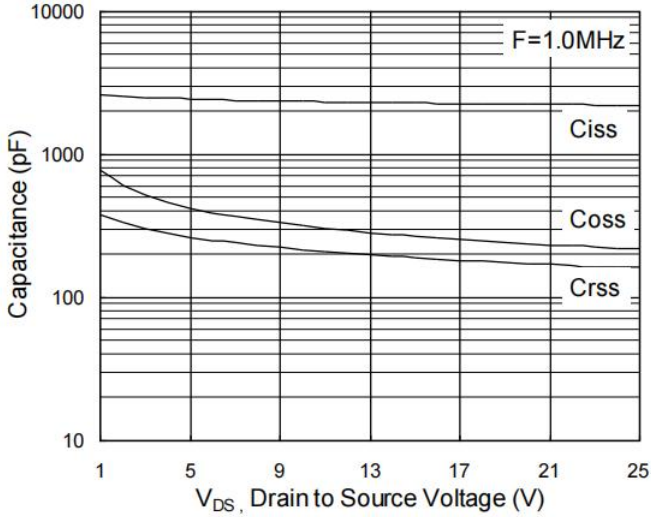


Fig.7 Capacitance

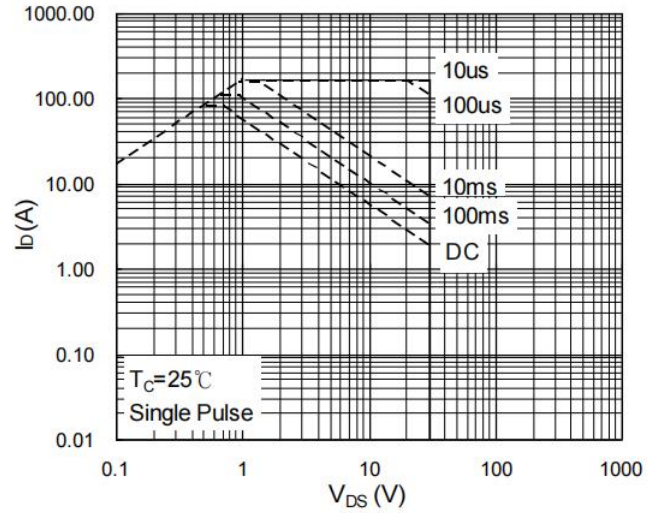


Fig.8 Safe Operating Area

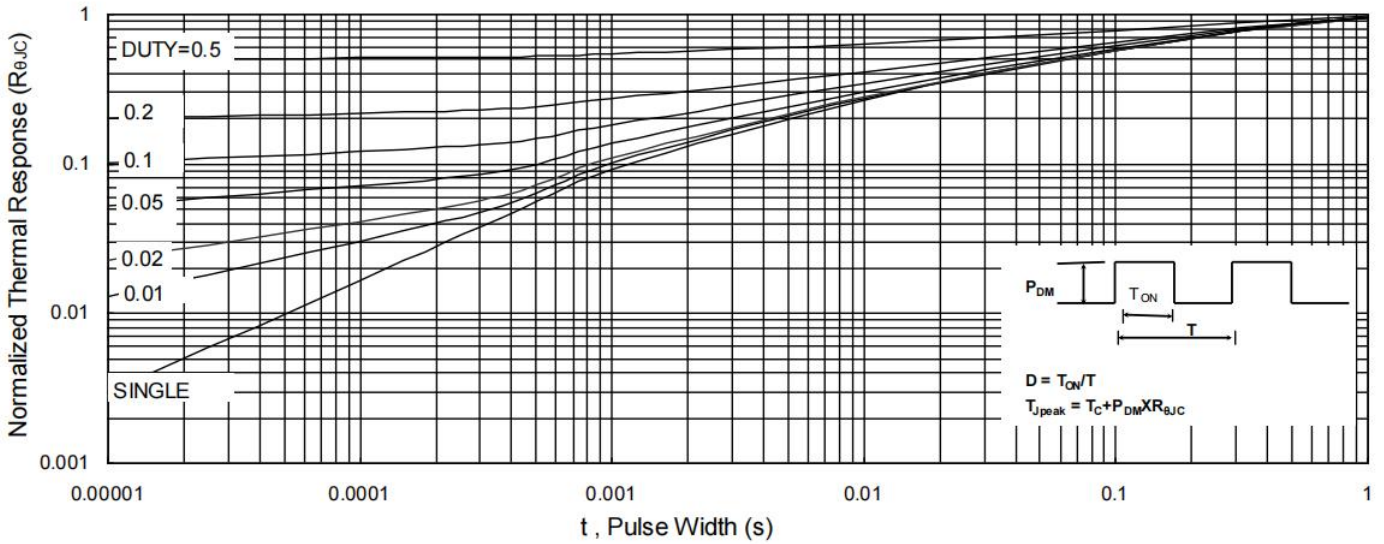


Fig.9 Normalized Maximum Transient Thermal Impedance

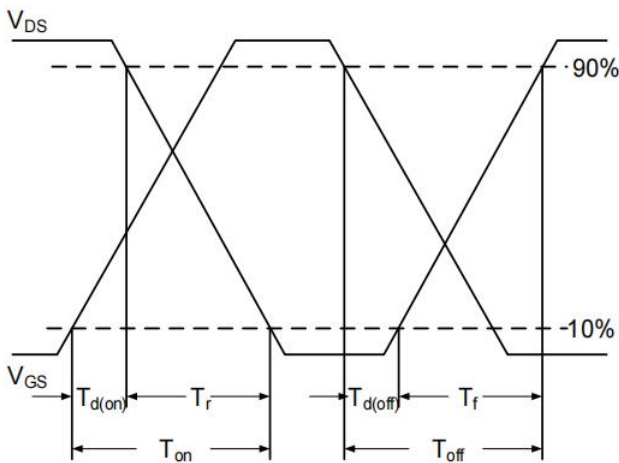


Fig.10 Switching Time Waveform

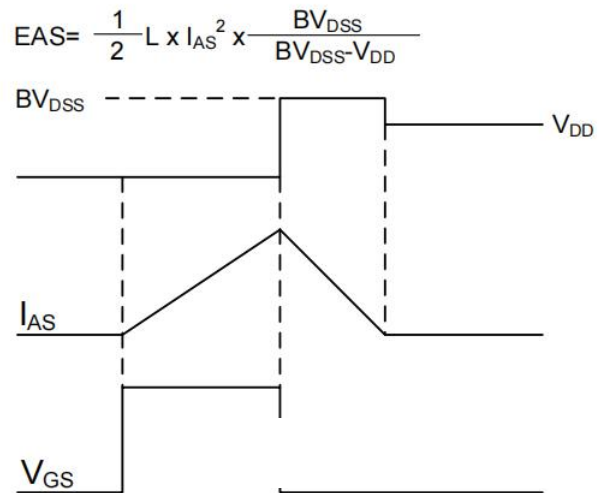
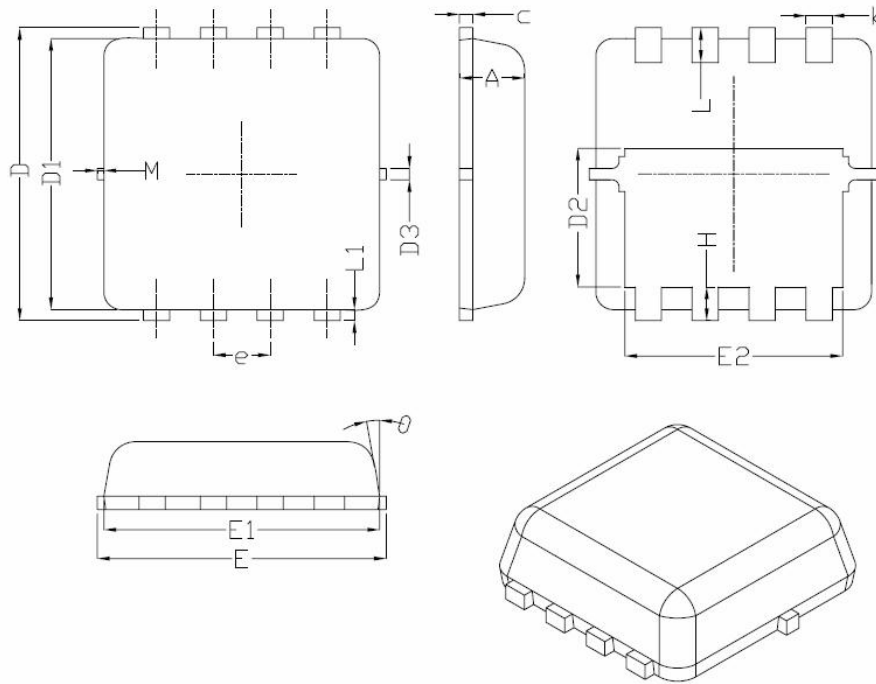


Fig.11 Unclamped Inductive Switching Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

DFN3X3-8L Package Information


Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.48	1.58	1.68
D3	-	0.13	-
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	-	0.13	-
M	*	*	0.15
θ		10°	12°

REEL SPECIFICATION

P/N	PKG	QTY
AONR36368-MS	DFN3X3-8L	5000

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